

# LM3045/LM3046/LM3086 Transistor Arrays

## **General Description**

The LM3045, LM3046 and LM3086 each consist of five general purpose silicon NPN transistors on a common monolithic substrate. Two of the transistors are internally connected to form a differentially-connected pair. The transistors are well suited to a wide variety of applications in low power system in the DC through VHF range. They may be used as discrete transistors in conventional circuits however, in addition, they provide the very significant inherent integrated circuit advantages of close electrical and thermal matching. The LM3045 is supplied in a 14-lead cavity dual-in-line package rated for operation over the full military temperature range. The LM3046 and LM3086 are electrically identical to the LM3045 but are supplied in a 14-lead molded dual-in-line package for applications requiring only a limited temperature range.

### **Features**

- Two matched pairs of transistors
   V<sub>BE</sub> matched ±5 mV
   Input offset current 2 μA max at I<sub>C</sub> = 1 mA
- Five general purpose monolithic transistors
- Operation from DC to 120 MHz
- Wide operating current range
- Low noise figure

■ Full military temperature range (LM3045)

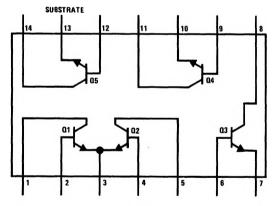
3.2 dB typ at 1 kHz -55°C to +125°C

### **Applications**

- General use in all types of signal processing systems operating anywhere in the frequency range from DC to VHF
- Custom designed differential amplifiers
- Temperature compensated amplifiers

## **Schematic and Connection Diagram**

#### **Dual-In-Line and Small Outline Packages**



**Top View** 

TL/H/7950-1

Order Number LM3045J, LM3046M, LM3046N or LM3086N See NS Package Number J14A, M14A or N14A

## **Absolute Maximum Ratings** (T<sub>A</sub> = 25°C)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/

Distributors for availability and specifications.	LM3	045	LM3046/		
	Each Transistor	Total Package	Each Transistor	Total Package	Units
Power Dissipation:				0	
T <sub>A</sub> = 25°C	300	750	300	750	mW
$T_A = 25^{\circ}C$ to 55°C			300	750	mW
T <sub>A</sub> > 55°C			Derate at 6.67		mW/°C
$T_A = 25^{\circ}C$ to 75°C	300	750			mW
T <sub>A</sub> > 75°C	Derate at 8				mW/°C
Collector to Emitter Voltage, V <sub>CEO</sub>	15		15		٧
Collector to Base Voltage, V <sub>CBO</sub>	20		20		V
Collector to Substrate Voltage, V <sub>CIO</sub> (Note 1)	20		20		٧
Emitter to Base Voltage, V <sub>EBO</sub>	5		5		٧
Collector Current, I <sub>C</sub>	50		50		mA
Operating Temperature Range	-55°C to +125°C		-40°C to +85°C		
Storage Temperature Range	-65°C to +150°C		-65°C to +85°C		
Soldering Information					
Dual-In-Line Package Soldering (10 Sec.)	260°C		260°C		
Small Outline Package			01500		
Vapor Phase (60 Seconds)			215°C		

Infrared (15 Seconds)

220°C

See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.

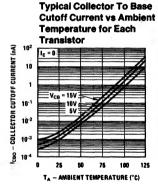
## Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise specified)

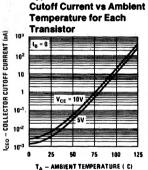
Parameter		Limits LM3045, LM3046			Limits LM3086			Units	
	Conditions								
		Min	Тур	Max	Min	Тур	Max		
Collector to Base Breakdown Voltage (V(BR)CBO)	$I_C = 10  \mu A$ , $I_E = 0$	20	60		20	60		٧	
Collector to Emitter Breakdown Voltage (V(BR)CEO)	$I_C \approx 1 \text{ mA}, I_B = 0$	15	24		15	24		V	
Collector to Substrate Breakdown Voltage (V(BR)CIO)	$I_{C} = 10 \mu\text{A}, I_{CI} = 0$	20	60		20	60		٧	
Emitter to Base Breakdown Voltage (V(BR)EBO)	$I_{E}$ 10 $\mu$ A, $I_{C}$ = 0	5	7		5	7		V	
Collector Cutoff Current (I <sub>CBO</sub> )	$V_{CB} = 10V, I_E = 0$		0.002	40		0.002	100	nA	
Collector Cutoff Current (I <sub>CEO</sub> )	$V_{CE} = 10V, I_{B} = 0$			0.5			5	μΑ	
Static Forward Current Transfer Ratio (Static Beta) (hFE)	$V_{CE} = 3V$ $\begin{cases} I_{C} = 10 \text{ mA} \\ I_{C} = 1 \text{ mA} \\ I_{C} = 10 \text{ \muA} \end{cases}$		100		-	100			
		40	100		40	100			
	lc = 10 μA		54			54			
Input Offset Current for Matched Pair Q <sub>1</sub> and Q <sub>2</sub>  I <sub>O1</sub> - I <sub>IO2</sub>	$V_{CE} = 3V, I_{C} = 1 \text{ mA}$		0.3	2				μА	
Base to Emitter Voltage (V <sub>BE</sub> )	$V_{CE} = 3V$ { $I_{E} = 1 \text{ mA}$ } $I_{E} = 10 \text{ mA}$		0.715			0.715		v	
	I <sub>E</sub> = 10 mA	0.800			0.800		7 °		
Magnitude of Input Offset Voltage for Differential Pair  V <sub>BE1</sub> - V <sub>BE2</sub>	$V_{CE} = 3V$ , $I_{C} = 1$ mA		0.45	5				m∨	
Magnitude of Input Offset Voltage for Isolated Transistors  VBE3 - VBE4 ,  VBE4 - VBE5 ,  VBE5 - VBE3	V <sub>CE</sub> = 3V, I <sub>C</sub> = 1 mA		0.45	5				m∨	
Temperature Coefficient of Base to Emitter Voltage $\left(\frac{\Delta V_{BE}}{\Delta T}\right)$	V <sub>CE</sub> = 3V, I <sub>C</sub> = 1 mA		-1.9			-1.9		mV/°C	
Collector to Emitter Saturation Voltage (V <sub>CE(SAT)</sub> )	$I_B = 1 \text{ mA}, I_C = 10 \text{ mA}$		0.23			0.23		٧	
Temperature Coefficient of Input Offset Voltage $\left(\frac{\Delta V_{10}}{\Delta T}\right)$	V <sub>CE</sub> = 3V, I <sub>C</sub> = 1 mA		1.1					μV/°C	

Note 1: The collector of each transistor of the LM3045, LM3046, and LM3086 is isolated from the substrate by an integral diode. The substrate (terminal 13) must be connected to the most negative point in the external circuit to maintain isolation between transistors and to provide for normal transistor action.

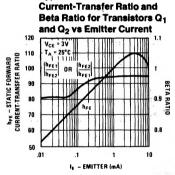
Parameter	Conditions	Min	Тур	Max	Units
Low Frequency Noise Figure (NF)	$f = 1 \text{ kHz}, V_{CE} = 3V,$ $I_{C} = 100 \mu\text{A}, R_{S} = 1 \text{ k}\Omega$		3.25		dB
LOW FREQUENCY, SMALL SIGNAL EQUIVALEN	IT CIRCUIT CHARACTERIS	rics			
Forward Current Transfer Ratio (hfe)	f = 1 kHz, V <sub>CE</sub> = 3V, I <sub>C</sub> = 1 mA		110 (LM3045, LM3046) (LM3086)		
Short Circuit input Impednace (hie)			3.5		kΩ
Open Circuit Output Impedance (hoe)			15.6		μmho
Open Circuit Reverse Voltage Transfer Ratio (hre)			1.8 x 10 <sup>-4</sup>		10
ADMITTANCE CHARACTERISTICS					
Forward Transfer Admittance (Yfe)	f = 1 MHz, V <sub>CE</sub> = 3V,		31 – j 1.5		
Input Admittance (Yie)	I <sub>C</sub> = 1 mA		0.3+J 0.04	(1)	8-
Output Admittance (Yoe)			0.001+j0.03	2	
Reverse Transfer Admittance (Yre)			See Curve	1	1
Gain Bandwidth Product (f <sub>T</sub> )	$V_{CE} = 3V, I_{C} = 3 \text{ mA}$	300	550	7	-9-
Emitter to Base Capacitance (CEB)	V <sub>EB</sub> = 3V, I <sub>E</sub> = 0		0.6		pF
Collector to Base Capacitance (C <sub>CB</sub> )	$V_{CB} = 3V, I_{C} = 0$		0.58		ρF
Collector to Substrate Capacitance (CCI)	$V_{CS} = 3V, I_{C} = 0$		2.8		ρF

## **Typical Performance Characteristics**



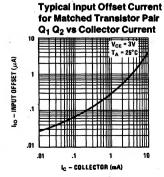


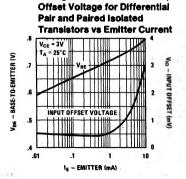
**Typical Collector To Emitter** 



**Typical Static Forward** 

TL/H/7950-2

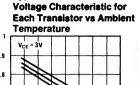




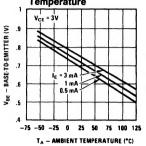
Typical Static Base To Emitter Voltage Characteristic and Input

TL/H/7950-3

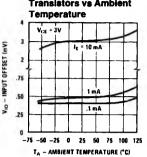
## **Typical Performance Characteristics** (Continued)



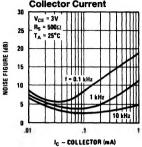
Typical Base To Emitter



**Typical Input Offset Voltage Characteristics for Differential** Pair and Paired Isolated Transistors vs Ambient Temperature

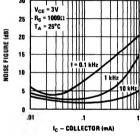




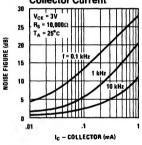


TL/H/7950-4

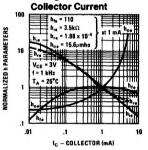
## Typical Noise Figure vs **Collector Current**



#### Typical Noise Figure vs **Collector Current**

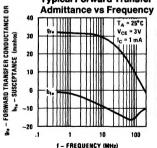


**Typical Normalized Forward Current Transfer Ratio, Short** Circuit Input Impedance, Open Circuit Output Impedance, and Open Circuit Reverse Voltage Transfer Ratio vs

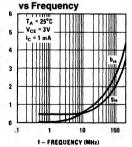


TL/H/7950-5

# **Typical Forward Transfer**

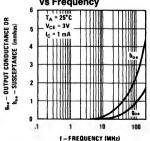


#### Typical Input Admittance vs Frequency



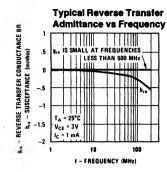
INPUT CONDUCTANCE - SUSCEPTANCE (mmhe

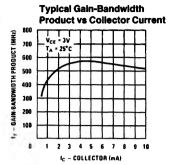
#### **Typical Output Admittance** vs Frequency



TL/H/7950-6

# Typical Performance Characteristics (Continued)





TL/H/7950-7